



May 15, 2017

NEWS RELEASE

Additional Increase in Production Capacity for Ultra-Thin Copper Foil with Carrier

— Increased monthly production capacity to 3.3 million m² —

Mitsui Mining & Smelting Co., Ltd. (President: Keiji Nishida; “Mitsui Kinzoku,” hereafter) is pleased to announce that it has decided to increase monthly production of its ultra-thin copper foil with carrier product to 3.3 million m².

Mitsui Kinzoku’s MicroThin™ ultra-thin copper foil with carrier product is much suitable for making fine circuit due to its foil thickness of 1.5μm - 5 μm and various surface treatments. With the availability of roll widths up to 1300 mm and stable carrier peeling strength, the product is highly regarded by customers for its contributions to improved productivity and higher process yields.

As informed in the news release issued on November 28, 2016, with smartphones becoming more sophisticated, consideration to apply MicroThin™ to HDI printed circuit boards for smartphones is progressing and demand is expected to undergo further growth from 2018 onward. Accordingly, Mitsui Kinzoku has decided to additionally increase the production capacity of the Malaysian plant (Mitsui Copper Foil (Malaysia) SDN. BHD.) to 1.8 million m² in July 2018 as the second step in series of MicroThin™ capacity expansion at the Malaysian plant. As the result, Mitsui Kinzoku’s MicroThin™ monthly production capacity will be 3.3 million m², allowing for even more stable supply to the market.

Mitsui Kinzoku will maintain its stable quality and adequate supply for current customers using the product for package substrates. At the same time, a supply framework to accommodate these new applications will be established as the company pursues an improved technological response and development capabilities alongside close coordination with customers. Moreover, Mitsui Kinzoku will accelerate the development of new future-oriented products under its slogan of Material Intelligence.

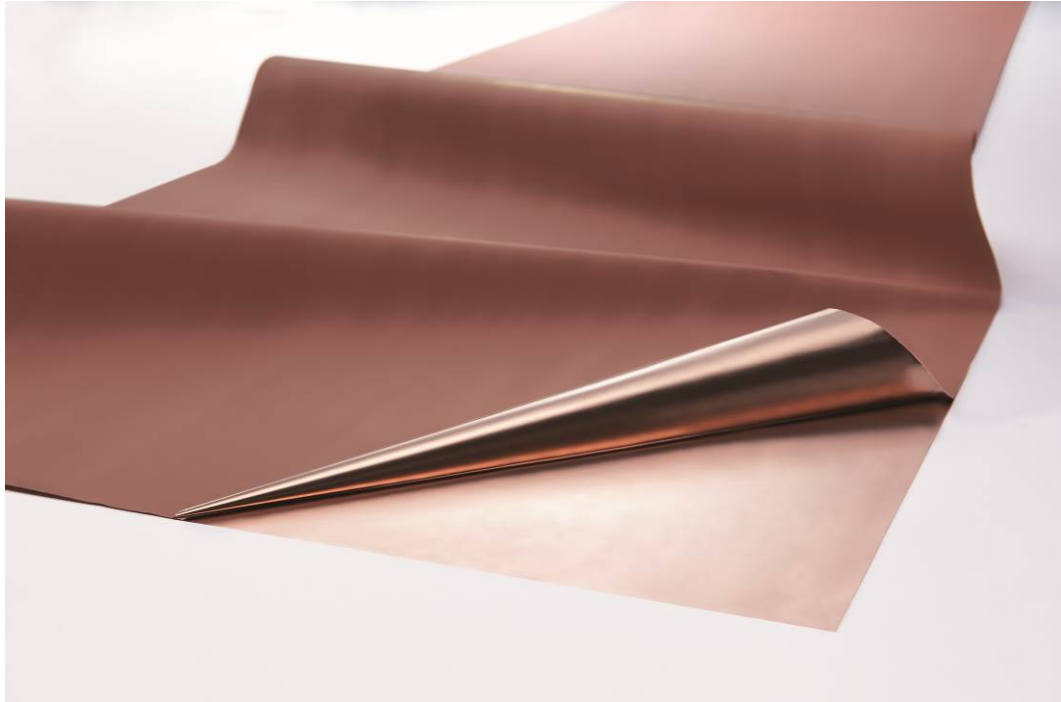
[Inquiries]

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MicroThin™ ultra-thin copper foil with carrier

(Reference)

Mitsui Copper Foil (Malaysia) SDN. BHD.

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| (1) Name | Mitsui Copper Foil (Malaysia) SDN. BHD. |
| (2) Location | Selangor, Malaysia |
| (3) President | Yuji Tejima |
| (4) Established | April 1989 |
| (5) Capital | 330,000,000 Malaysian Ringgit |
| (6) Investment | Mitsui Kinzoku (100%) |
| (7) Business Activities | Manufacturing of copper foil for printed circuit boards |